a [second substrate] motherboard having at least one contact;

at least one solder ball extending between said at least one [first] substrate contact and said at least one [second substrate] motherboard contact, wherein said at least one solder ball is attached to one of said at least one [first] substrate contact and said at least one motherboard contact; and

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a compression mechanism for imparting pressure between said [first] substrate and said [second substrate] motherboard.

2. (First Amended) The microelectronic component assembly of claim 1, wherein said [first] substrate comprises a microelectronic device package.

4. (First Amended) The microelectronic component assembly of claim 1, wherein said [first] substrate comprises a microelectronic device.

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5. (First Amended) The microelectronic component assembly of claim 1, wherein said solder ball is attached to said at least one substrate contact and at least one [second substrate] motherboard contact comprises a recess defined by at least one sidewall extending into said [second substrate] motherboard.

6. (First Amended) The microelectronic component assembly of claim 5, wherein said at least one recessed [second substrate] motherboard contact includes a width which is substantially the same as a diameter of said solder ball.

7. (First Amended) The microelectronic component assembly of claim 5, wherein said at least one recessed [second substrate] motherboard contact has a semispherical surface which is substantially the same radius as a radius of said solder ball.

12. (First Amended) A microelectronic component assembly, comprising:

a [first] substrate having a first surface and a second surface, wherein said first substrate first surface includes at least one contact;

a [second substrate] motherboard having a first surface and a second surface; wherein said [second substrate] motherboard first surface includes at least one contact;

at least one solder ball extending between said at least one [first] substrate first surface contact and said at least one [second substrate] motherboard first surface contact, wherein said at least one solder ball is attached to one of said at least one [first] substrate first surface contact and said at least one [second substrate] motherboard first surface contact; and

a support structure for imparting pressure between said [first] substrate and said [second substrate] motherboard.

13. (First Amended) The microelectronic component assembly of claim 12, wherein said support structure comprises:

a frame surrounding a portion of said [first] substrate,

a backing plate abutting said [second substrate second surface] motherboard;

a thermal plate extending over said frame and adjacent said [first] substrate second

surface; and

a plurality of retention devices extending through said backing plate, said frame, and said thermal plate.

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15. (First Amended) The microelectronic component assembly of claim 12, wherein said [first] substrate comprises a microelectronic device package including a microelectronic device attached to and in electrical contact with a first surface of an interposer substrate, and wherein said at least [first] substrate first surface contact comprises at least one contact on a second surface of said interposer substrate.

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16. (First Amended) The microelectronic component assembly of claim 15, wherein said support frame comprises

a frame surrounding a portion of said [first] substrate,

a backing plate abutting said [second substrate] motherboard second surface;

a thermal plate extending over said frame and adjacent said [first] substrate second surface;

a plurality of retention devices extending through said backing plate, said frame[;], and the thermal plate; and

a resilient spacer extending between said thermal plate and said interposer substrate.

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23. (First Amended) A substrate contact for forming a non-reflow electrical contact with a solder ball, comprising:

a recess [define] defined in a substrate by at least one surface extending into said substrate having at least one substantially vertical side wall; and

a conductive material layered in said recess, wherein said conductive material is also layered on said at least one substantially vertical side wall.

25. (First Amended) The substrate contact of claim [24] 23, further including a width of said recess, including said layered conductive material, which is substantially the same as a diameter of said solder ball.

[27] 28. (First Amended) A substrate contact for forming a non-reflow electrical contact with a solder ball, comprising:

a recess define in a substrate by at least one surface extending into said substrate; and

a conductive material layered over said recess forming a void in said recess.

Please add claims 29-33, as follows:

-- 29. The microelectronic component assembly of claim 1, wherein said solder ball is attached to said motherboard contact and at least one substrate contact comprises a recess defined by at least one sidewall extending into said substrate.

30. The microelectronic component assembly of claim 29, wherein said at least one recessed substrate contact includes a width which is substantially the same as a diameter of said solder ball.

31. The microelectronic component assembly of claim 29, wherein said at least one recessed substrate contact has a semispherical surface which is substantially the same radius as a radius of said solder ball.

32. A substrate contact for forming a non-reflow electrical contact with a solder ball, comprising:

a semispherical recess defined in a substrate by at least one surface extending into said substrate;

a conductive material layered in said semispherical recess; and

an upper surface of said conductive material layer having a radius which is substantially the same as a radius of said solder ball.

33. The substrate contact of claim 32, further including a resilient material disposed between said substrate and said conductive material layer. --

Please cancel claims 3, 8-11, 17-22, 24, 26 (previously misnumbered as claim 25), and 27 (previously misnumbered as claim 26), without prejudice.

## REMARKS

Claims 1, 2, 4-7, 12-16, 23, 25, and 28-33 remain in the application. Claims 1, 2, 4-7, 12, 13, 15, 16, 23, 25, and 28 (previously misnumbered as claim 27) have been amended. Claim 8-11 and 17-22 have been canceled without prejudice. The originally filed application was filed